



Holography, 3D Imaging and 3D Display Volume II

Guest Editors:

Prof. Dr. Ting-Chung Poon

Prof. Dr. Yaping Zhang

Prof. Dr. Liangcai Cao

Prof. Dr. Hiroshi Yoshikawa

Prof. Dr. Taegeun Kim

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submissions:

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Message from the Guest Editors

Dear Colleagues,

Modern holographic techniques have been successfully applied in many important areas, such as 3D inspection, 3D microscopy, metrology and profilometry, augmented reality, and industrial informatics. This Special Issue covers selected pieces of cutting-edge research works, ranging from low-level acquisition to the high-level analysis, processing, and manipulation of holographic information. This Special Issue also serves as a comprehensive review of the existing state-of-the-art techniques in 3D imaging and 3D display, and is intended to provide broad insight into the future development of these disciplines. Your contributions toward the Issue are greatly appreciated. If you have any questions regarding the Special Issue, please feel free to contact us.

Prof. Dr. Ting-Chung Poon
Prof. Dr. Yaping Zhang
Assoc. Prof. Dr. Liangcai Cao
Prof. Dr. Hiroshi Yoshikawa
Prof. Dr. Taegeun Kim
Guest Editors





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
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